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## Dainippon Screen Announces a Next Generation Single Wafer Cleaning System Combining Five Process Application Modules

Kyoto, Japan, November 27, 2003 ---- Dainippon Screen Mfg. Co., Ltd., (Headquarters: Kyoto; Japan / President: Akira Ishida) announces the release of a next generation single wafer cleaning system, "SU-3000", which combines five of its leading-edge process application modules into a single platform.

This new 300mm wafer process platform provides customers with the flexibility needed to address the wet clean/etch challenges on their most advanced product technologies. The SU-3000 combines five proven, field-tested process modules available from DNS previously on stand-alone tools. These include dual-sided spin scrub cleaning from the SS-3000, FEOL aqueous (acid/alkaline) cleaning from the MP-3000, BEOL solvent cleaning for post-etch polymer removal from the SR-3000, bevel edge etch and clean for advanced Copper interconnect processing from the MP-3000CB, and finally high selectivity vapor etching from the VP-812C. The SU-3000 successfully unifies this broad range of process capabilities into a single, flexible process tool, opening a broad range of new possibilities for advanced device fabrication.

The leading-edge SU-3000 system, which can combine any two of the five types of application modules (for a total of four modules) on a single platform, provides the user several unique capabilities. For example, with a combination of the SS and MP modules, the SU-3000 enables the backside scrub cleaning and frontside wet etch and surface preparation to be performed in a

single system. By combining the VP and MP modules, residues remaining after selective etching in the VP module can be removed by chemical cleaning in the MP module. Other flexible unit combinations can also support new processes demanded by new materials in both the FEOL and BEOL, such as high-k dielectrics for advanced gates, and low-k dielectrics for advanced interconnect. The SU-3000 combines Dainippon Screen's industry leading reliability un-paralleled process flexibility in a small footprint, single wafer tool.



The SU-3000, the single wafer cleaning system

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